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(54) Title: HIGH SPEED IDC MODULAR JACK**(57) Abstract**

A high speed IDC modular jack wherein wires are grouped into a first group and a second group and wherein the wires in the first group are longer than the wires in the second group and are in a separate plane from said wires in the second group such that cross talk is reduced. First and second conductors extend in a first plane (30) perpendicularly into this base section (12) adjacent its first end (14). It then extends longitudinally through the base section (12) and extends perpendicularly into the angular section (22) in a second (32) and third plane (34) respectively. Third and fourth conductors extend in a fourth plane (36) perpendicularly into the base section (12) adjacent its second end (16) and then extend into the angular section (22) of an insulative member in the second (32) and third (34) plane respectively.

